

# MBD54DWT1

Preferred Device

## Dual Schottky Barrier Diodes

These Schottky barrier diodes are designed for high speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand held and portable applications where space is limited.

### Features

- Extremely Fast Switching Speed
- Low Forward Voltage – 0.35 V @  $I_F = 10$  mAdc
- Pb-Free Package is Available

### MAXIMUM RATINGS ( $T_J = 125^\circ\text{C}$ unless otherwise noted)

Rating	Symbol	Value	Unit
Reverse Voltage	$V_R$	30	V
Forward Power Dissipation @ $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_F$	150 1.2	mW mW/ $^\circ\text{C}$
Forward Current (DC)	$I_F$	200 Max	mA
Junction Temperature	$T_J$	125 Max	$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	-55 to +150	$^\circ\text{C}$

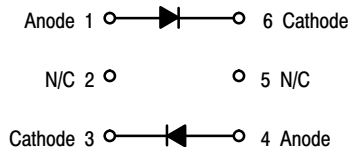
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.



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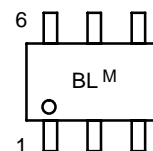
## 30 VOLTS DUAL HOT-CARRIER DETECTOR AND SWITCHING DIODES



### MARKING DIAGRAM



SOT-363  
CASE 419B-01  
STYLE 6



M = Date Code

### ORDERING INFORMATION

Device	Package	Shipping†
MBD54DWT1	SOT-363	3000/Tape & Reel
MBD54DWT1G	SOT-363 (Pb-Free)	3000/Tape & Reel

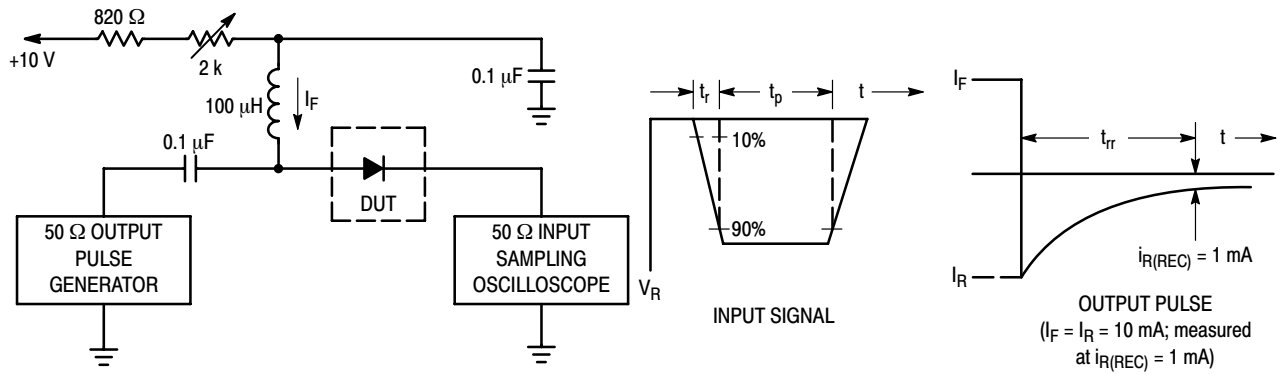
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

**Preferred** devices are recommended choices for future use and best overall value.

# MBD54DWT1

## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted) (EACH DIODE)

Characteristic	Symbol	Min	Typ	Max	Unit
Reverse Breakdown Voltage ( $I_R = 10\ \mu\text{A}$ )	$V_{(BR)R}$	30	–	–	V
Total Capacitance ( $V_R = 1.0\ \text{V}$ , $f = 1.0\ \text{MHz}$ )	$C_T$	–	7.6	10	pF
Reverse Leakage ( $V_R = 25\ \text{V}$ )	$I_R$	–	0.5	2.0	$\mu\text{A}$ dc
Forward Voltage ( $I_F = 0.1\ \text{mA}$ dc)	$V_F$	–	0.22	0.24	Vdc
Forward Voltage ( $I_F = 30\ \text{mA}$ dc)	$V_F$	–	0.41	0.5	Vdc
Forward Voltage ( $I_F = 100\ \text{mA}$ dc)	$V_F$	–	0.52	1.0	Vdc
Reverse Recovery Time ( $I_F = I_R = 10\ \text{mA}$ dc, $I_{R(REC)} = 1.0\ \text{mA}$ dc) (Figure 1)	$t_{rr}$	–	–	5.0	ns
Forward Voltage ( $I_F = 1.0\ \text{mA}$ dc)	$V_F$	–	0.29	0.32	Vdc
Forward Voltage ( $I_F = 10\ \text{mA}$ dc)	$V_F$	–	0.35	0.40	Vdc
Forward Current (DC)	$I_F$	–	–	200	mA
Repetitive Peak Forward Current	$I_{FRM}$	–	–	300	mA
Non-Repetitive Peak Forward Current ( $t < 1.0\ \text{s}$ )	$I_{FSM}$	–	–	600	mA



- Notes: 1. A 2.0 k $\Omega$  variable resistor adjusted for a Forward Current ( $I_F$ ) of 10 mA.  
 2. Input pulse is adjusted so  $I_{R(\text{peak})}$  is equal to 10 mA.  
 3.  $t_p \gg t_{rr}$

Figure 1. Recovery Time Equivalent Test Circuit

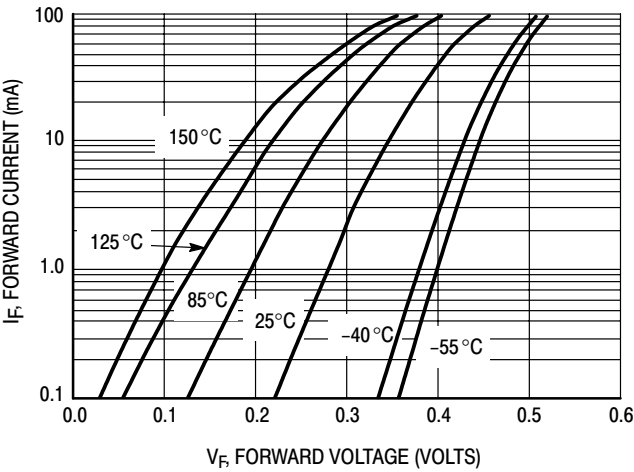


Figure 2. Forward Voltage

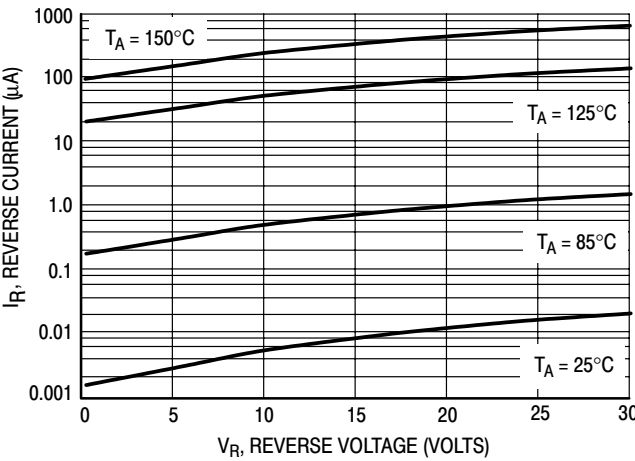


Figure 3. Leakage Current

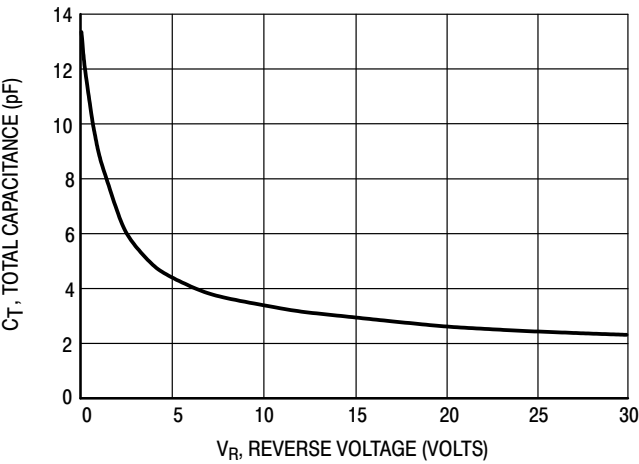
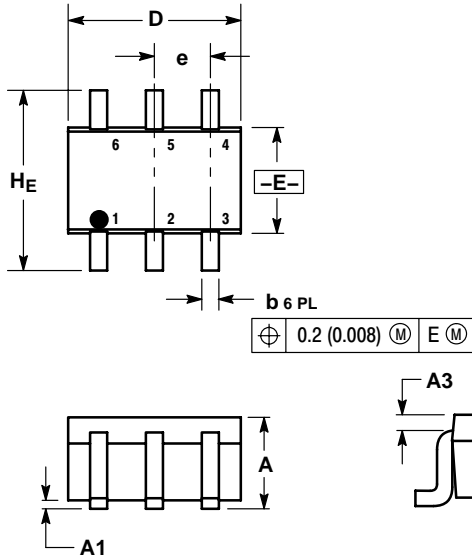


Figure 4. Total Capacitance

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## PACKAGE DIMENSIONS

SC-88/SC70-6/SOT-363  
CASE 419B-02  
ISSUE V



### NOTES:

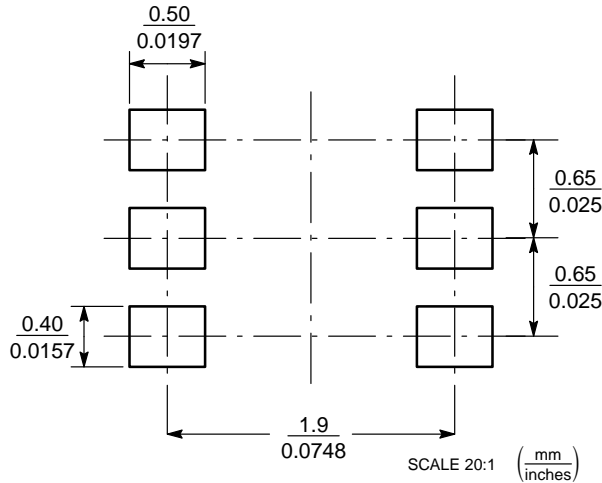
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 419B-01 OBSOLETE, NEW STANDARD 419B-02.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.95	1.10	0.031	0.037	0.043
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3	0.20 REF			0.008 REF		
b	0.10	0.21	0.30	0.004	0.008	0.012
C	0.10	0.14	0.25	0.004	0.005	0.010
D	1.80	2.00	2.20	0.070	0.078	0.086
E	1.15	1.25	1.35	0.045	0.049	0.053
e	0.65 BSC			0.026 BSC		
L	0.10	0.20	0.30	0.004	0.008	0.012
HE	2.00	2.10	2.20	0.078	0.082	0.086

### STYLE 6:

- PIN 1: ANODE 2  
2: N/C  
3: CATHODE 1  
4: ANODE 1  
5: N/C  
6: CATHODE 2

## SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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